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JP59047751A2: COPPER ALLOY FOR LEAD WIRE MATERIAL OF SEMICONDUCTOR DEVICE

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Country: **JP** Japan

Kind:

Inventor(s): **KAWAUCHI SUSUMU
TSUJI MASAHIRO
YAMAMOTO MICHIHARU**

Applicant(s): **NIPPON MINING CO LTD**
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Issued/Filed Dates: **March 17, 1984 / Sept. 13, 1982**

Application Number: **JP1982000158212**

IPC Class: **H01L 23/48; C22C 9/00;**

Abstract: **Purpose:** To obtain a lead wire material having suitable characteristics, particularly excellent adhesion of plating by defining respective components of copper- nickel-zinc alloy and limiting amounts of diversified kinds of sub-components to be mixed.
Constitution: An alloy consisting of nickel of 1.5W10wt%, zinc of 5W20wt%, oxygen of 0.0020wt% or less and remainder consisting of copper and inevitable impurities is used, or an alloy consisting of one or more metals in total weight of 0.001W2.0wt% selected from phosphorus of 0.001W0.1wt%, tin of 0.01W1.0wt%, iron of 0.005W1.0wt%, cobalt of 0.01W1.0wt%, chromium of 0.01W1.0wt%, aluminum of 0.01W1.0wt%, magnesium of 0.01W1.0wt%, manganese of 0.01W1.0wt%, titanium of 0.01W1.0wt%, zirconium of 0.01W1.0wt% and beryllium of 0.01W 1.0wt% and remainder consisting of copper and inevitable impurities are used.
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Other Abstract Info: none

Foreign References: (No patents reference this one)



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